

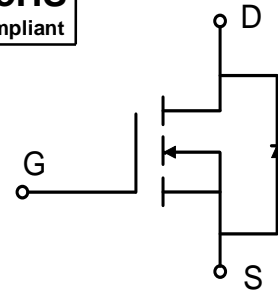
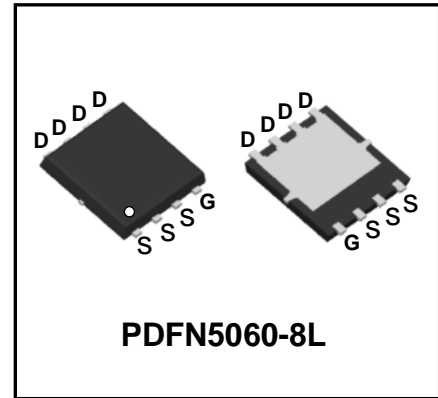
60V N-Channel Enhancement Mode Power MOSFET

Description

WMB64N10T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Features

- $V_{DS} = 100V$, $I_D = 64A$
 $R_{DS(on)} < 14m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(on)} < 17m\Omega$ @ $V_{GS} = 4.5V$
- Green Device Available
- 100% EAS Guaranteed
- Low Gate Charge
- Advanced High Cell Density Trench Technology



Applications

- Power Management Switches
- Synchronous Rectification for AC/DC Quick Charger

Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source voltage		V_{DS}	100	V
Gate-Source voltage		V_{GS}	± 20	V
Continuous Drain Current@10V ^{1,6}	$T_C=25^\circ C$	I_D	64	A
	$T_C=100^\circ C$		40	
Pulsed Drain Current ²		I_{DM}	130	A
Single Pulse Avalanche Energy ³		EAS	125	mJ
Avalanche Current		I_{AS}	50	A
Total Power Dissipation ⁴	$T_C=25^\circ C$	P_D	89	W
Operating Junction and Storage Temperature Range		T_J , T_{STG}	-55 to +150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ¹	R_{θJA}	62	$^\circ C/W$
Thermal Resistance from Junction-to-Case ¹	R_{θJC}	1.4	$^\circ C/W$

Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V	
Gate-body Leakage Current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA	
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	I_{DSS}	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	μA
	$T_J=55^\circ\text{C}$			-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	-	2.4	V	
Drain-Source On-Resistance ²	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 10A$	-	-	14	m Ω	
		$V_{GS} = 4.5V, I_D = 8A$	-	-	17		
Forward Transconductance	g_{fs}	$V_{DS} = 5V, I_D = 20A$	-	31	-	S	
Dynamic Characteristics							
Input Capacitance	C_{iss}	$V_{DS} = 25V, V_{GS} = 0V, f = 1\text{MHz}$	-	4708	-	pF	
Output Capacitance	C_{oss}		-	225	-		
Reverse Transfer Capacitance	C_{rss}		-	170	-		
Switching Characteristics							
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	-	1.2	-	Ω	
Total Gate Charge(10V)	Q_g	$V_{GS} = 10V, V_{DS} = 80V, I_D = 10A$	-	75	-	nC	
Gate-Source Charge	Q_{gs}		-	15.5	-		
Gate-Drain Charge	Q_{gd}		-	20.3	-		
Turn-On Delay Time	$t_{d(on)}$		-	18.5	-		nS
Rise Time	t_r	$V_{GS} = 10V, V_{DD} = 40V,$ $R_G = 3.3\Omega, I_D = 10A$	-	8.8	-		
Turn-Off Delay Time	$t_{d(off)}$		-	58.8	-		
Fall Time	t_f		-	15.8	-		
Drain-source body diode Characteristics							
Diode Forward Voltage ²	V_{SD}	$I_S = 1A, V_{GS} = 0V$	-	-	1.2	V	
Continuous Source Current ^{1,5}	I_S	$V_G=V_D=0V, \text{Force Current}$	-	-	64	A	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 10A, dI/dt = 100A/\mu s$	-	24	-	nS	
Body Diode Reverse Recovery Charge	Q_{rr}		-	28	-	nC	

Notes:

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=50A$
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

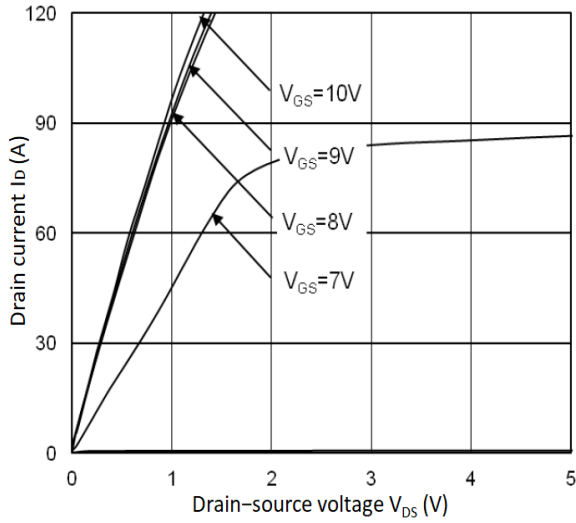


Figure 1. Output Characteristics

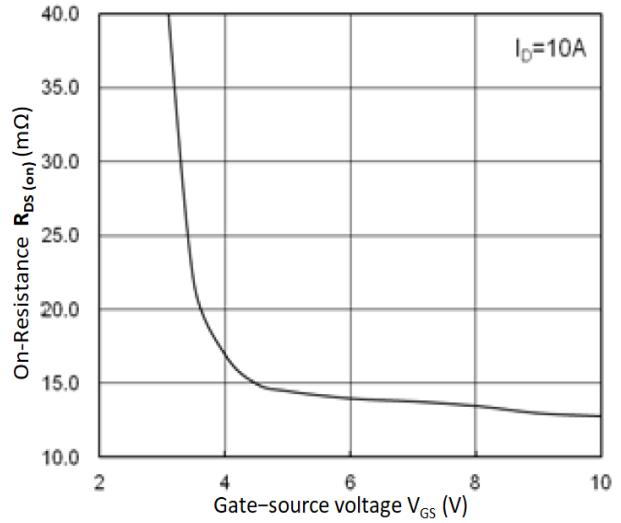


Figure 2. $R_{DS(on)}$ vs. V_{GS}

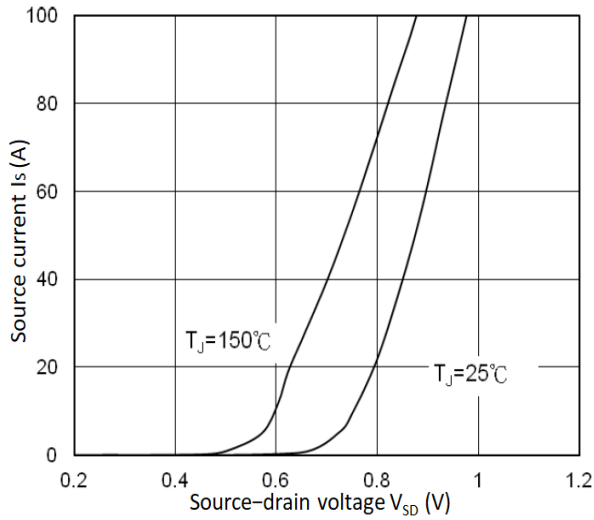


Figure 3. Forward Characteristics of Reverse

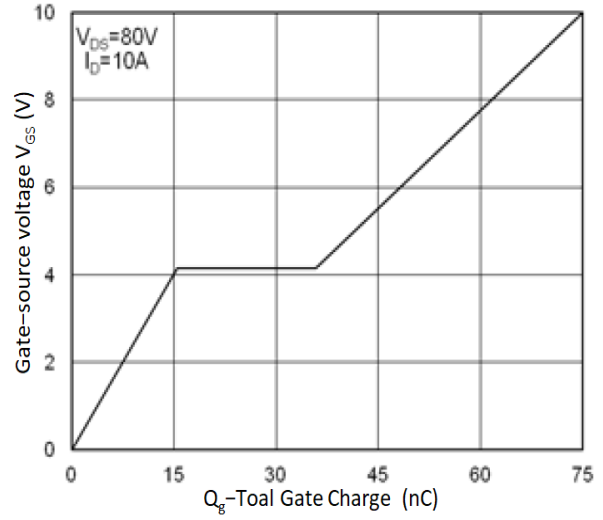


Figure 4. Gate Charge Characteristics

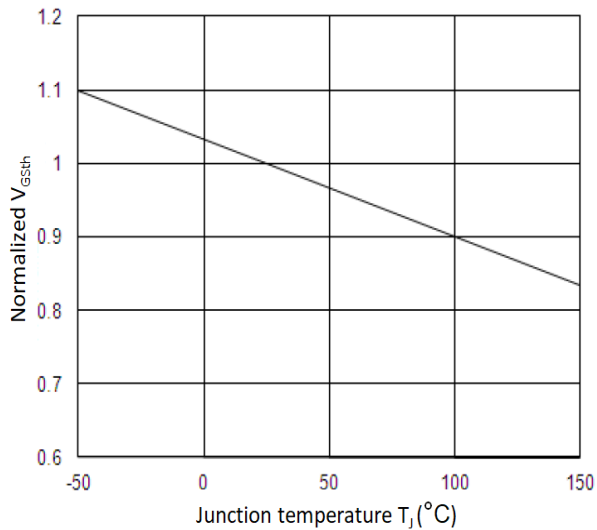


Figure 5. Normalized $V_{GS(th)}$ vs. T_J

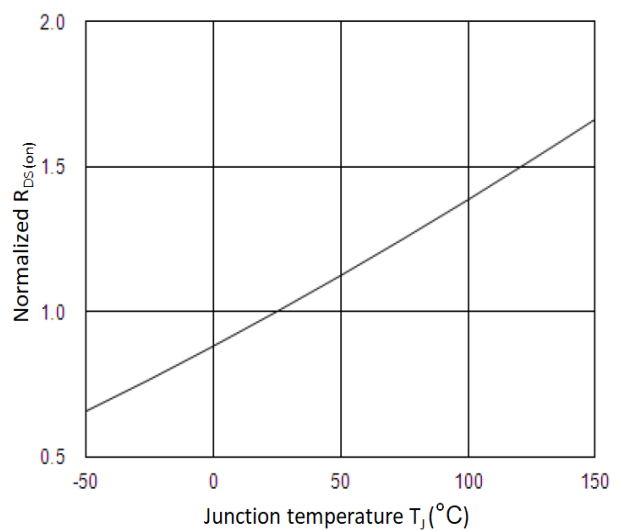


Figure 6. Normalized $R_{DS(on)}$ vs. T_J

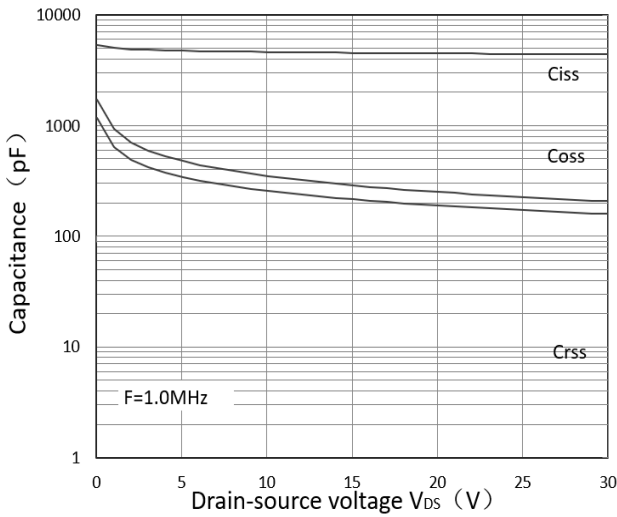


Figure 7. Capacitance Characteristics

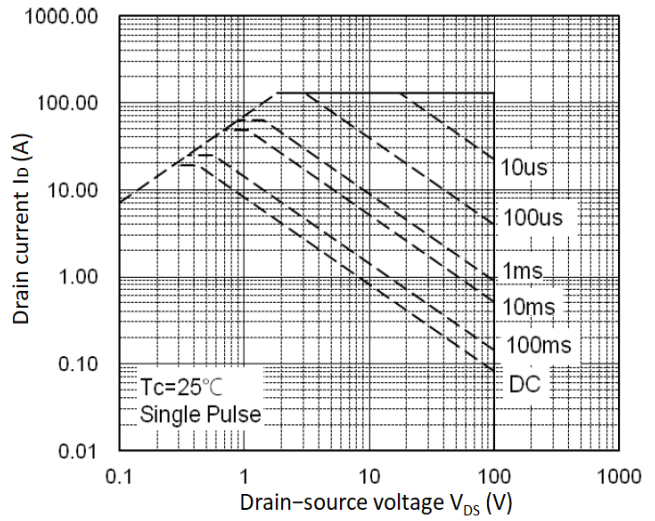


Figure 8. Safe Operating Area

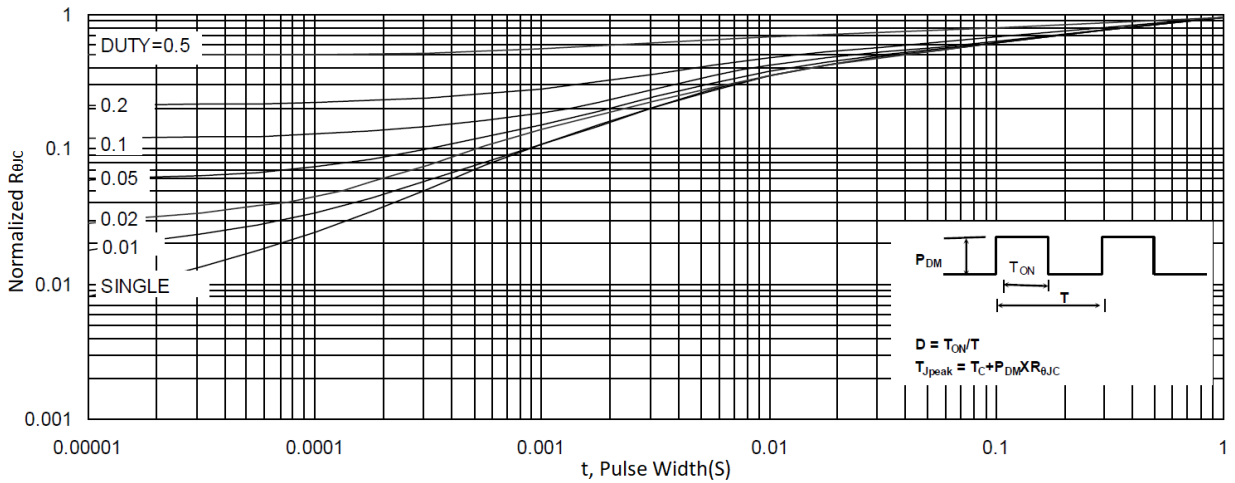


Figure 9. Normalized Maximum Transient Thermal Impedance

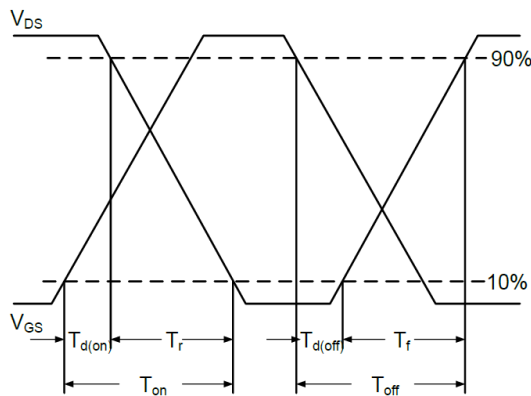


Figure 10. Switching Time Waveform

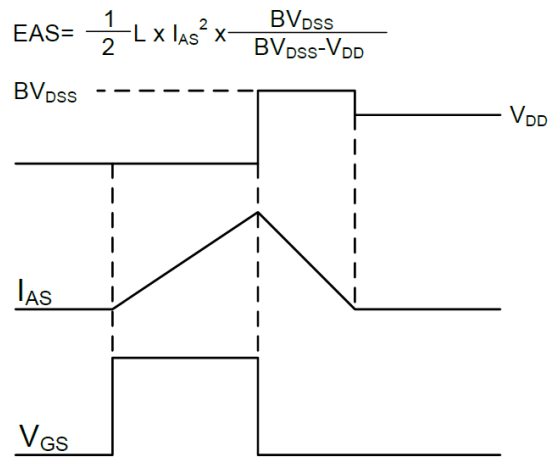
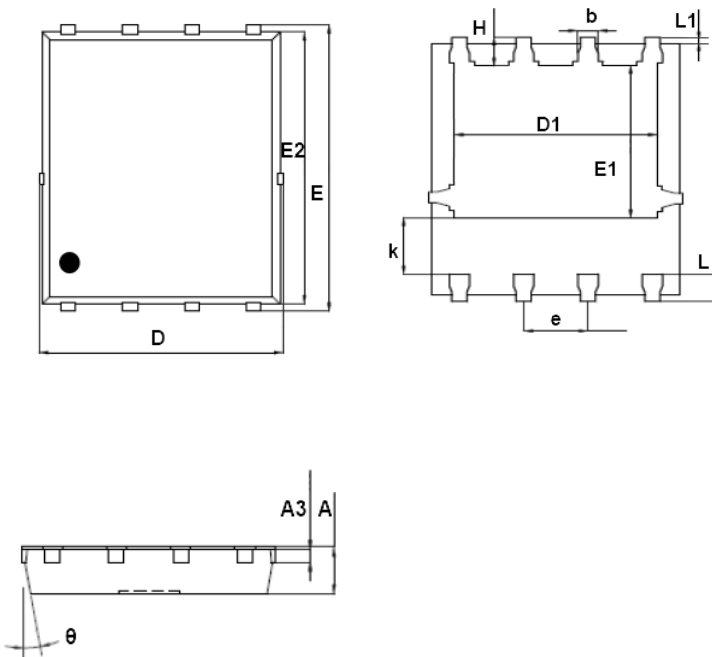


Figure 11. Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Mechanical Dimensions for PDFN5060-8L

COMMON DIMENSIONS

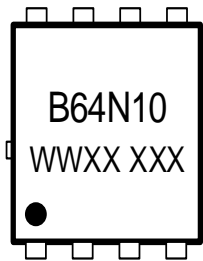


SYMBOL	MM	
	MIN	MAX
A	0.90	1.17
A3	0.20	0.35
D	4.80	5.40
E	5.90	6.15
D1	3.61	4.31
E1	3.3	3.78
E2	5.65	5.85
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
θ	0°	12°

Ordering Information

Part	Package	Marking	Packing method
WMB64N10T1	PDFN5060-8L	B64N10	Tape and Reel

Marking Information



B64N10= Device code

WWXX XXX= Date code


Contact Information

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